



**Research Institute for Science and Engineering  
Waseda University**

# **Optimization of high average power FEL for EUV lithography application**

Akira Endo, Kazuyuki Sakaue,

Masakazu Washio : Waseda University

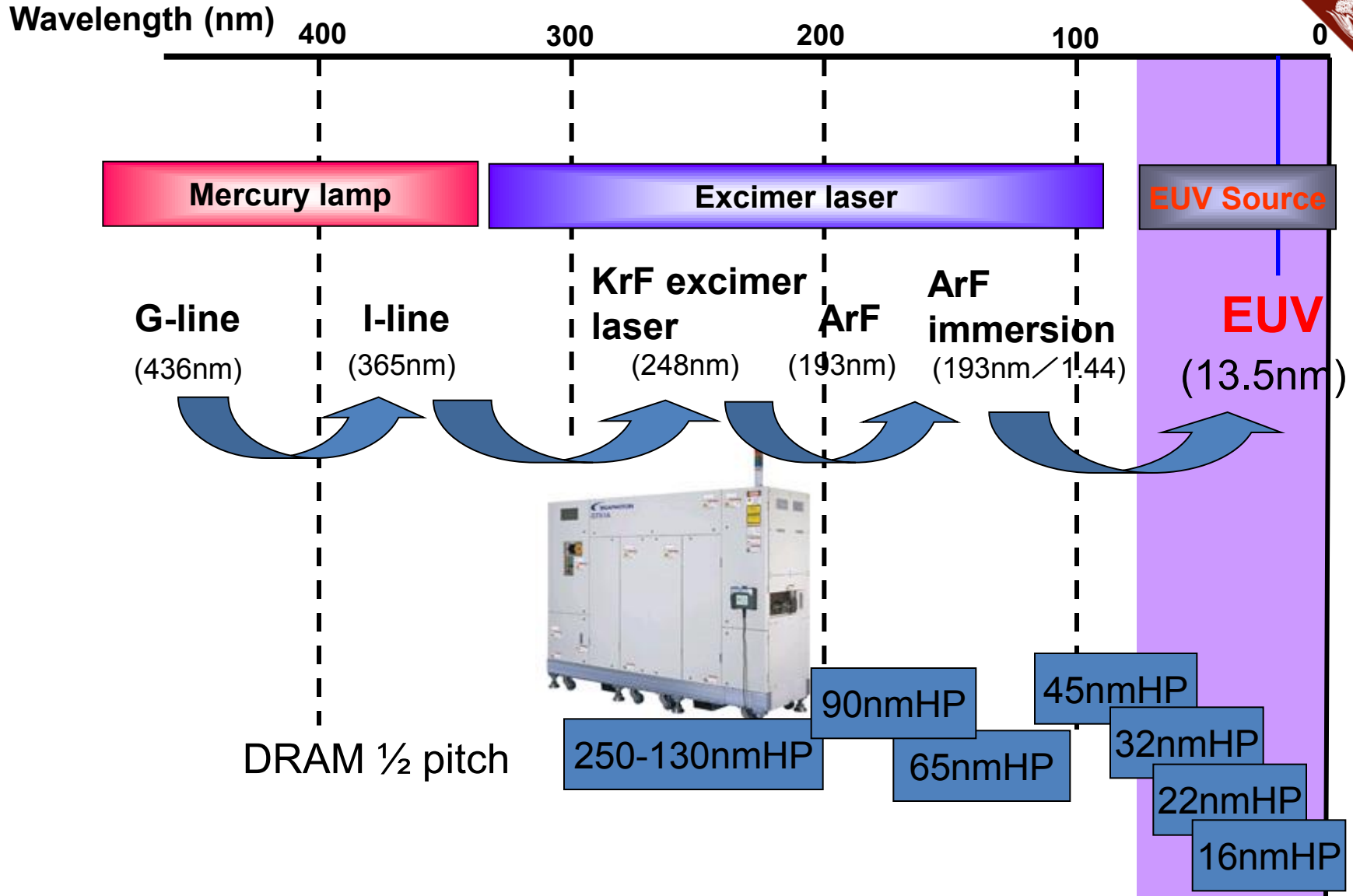
Hakaru Mizoguchi : Gigaphoton Inc.



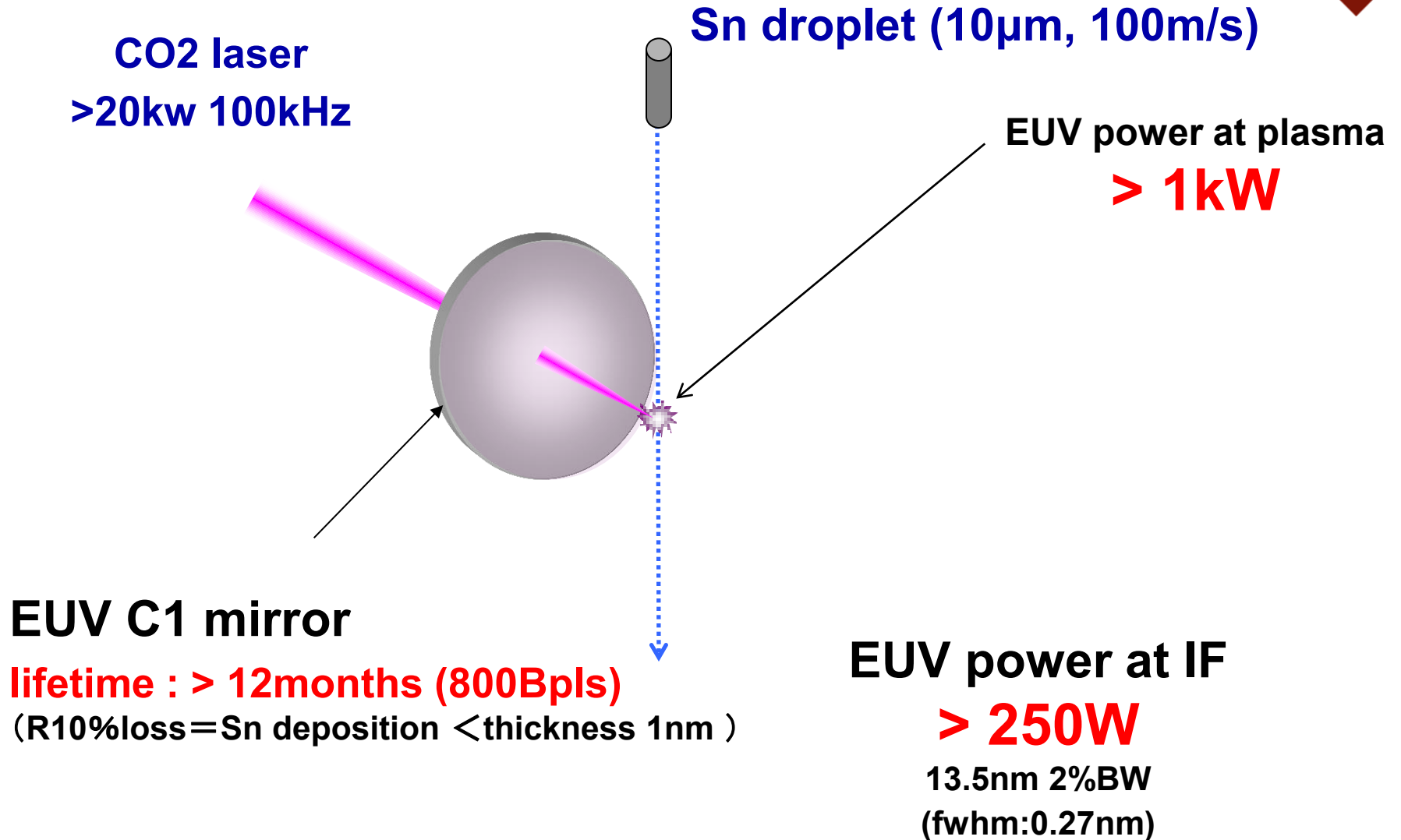
# Outline

- EUV lithography source
- Power scaling of SASE FEL technology
- EUV resist under FEL pulses
- Spatial coherence and EUV homogenizer
- Temporal smoothing and HGHG
- Laser seeding technology at MHz
- Perspective

# Trends of optical lithography



# Typical configuration of EUV source



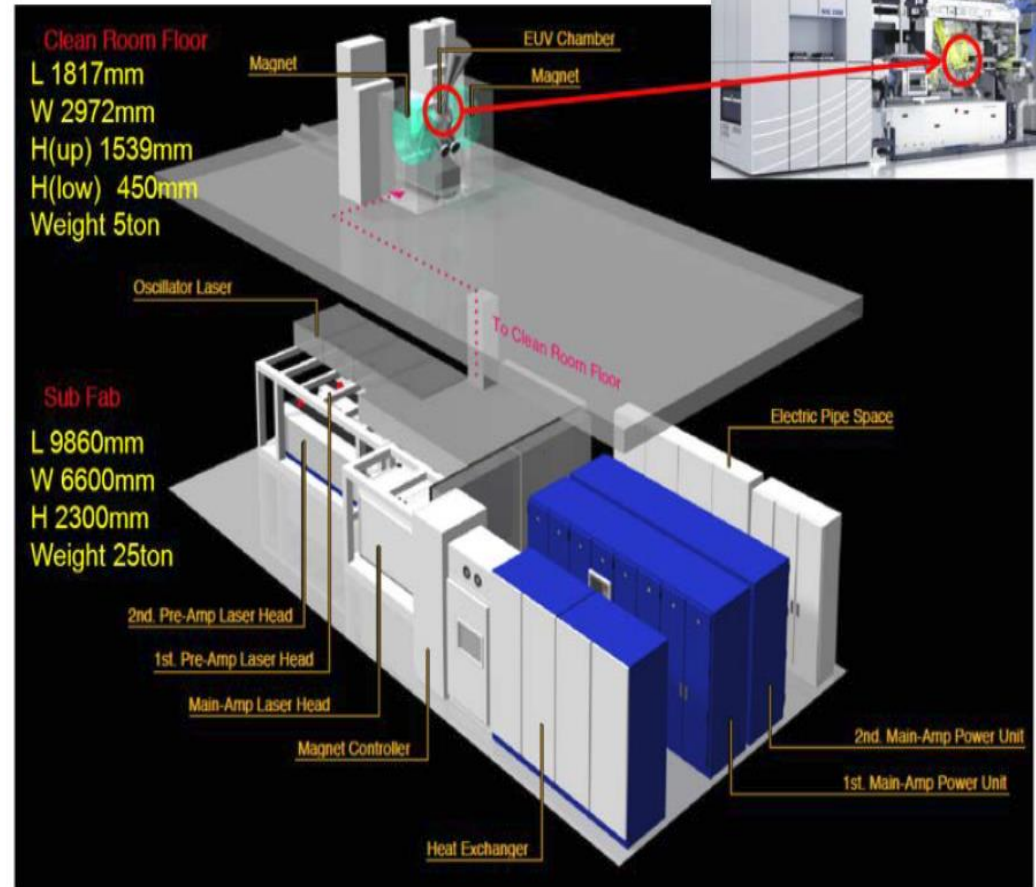
# Power-up Scenario of HVM Sources

## Layout of 250W EUV light source

### First HVM EUV Source

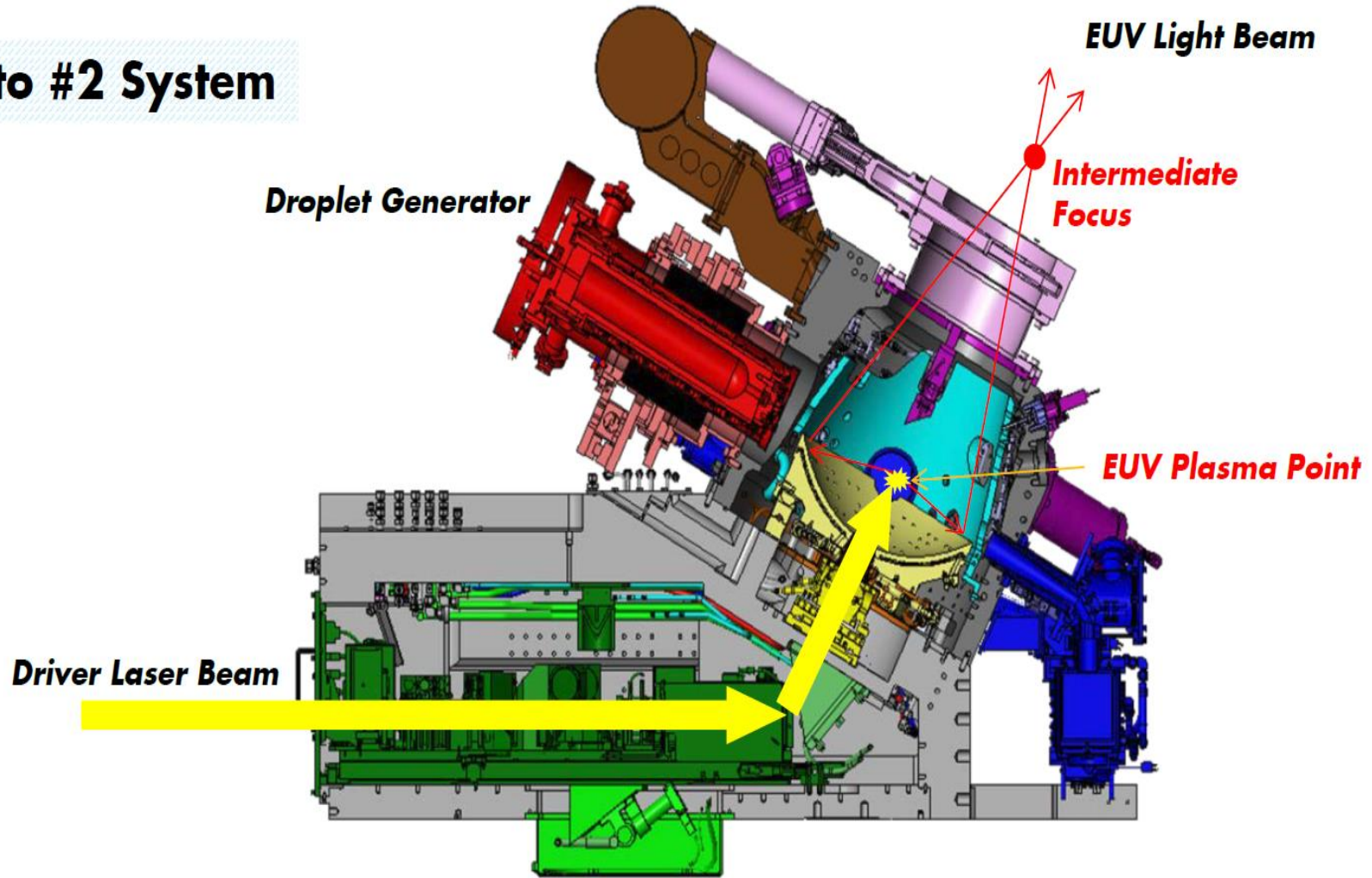
- Gigaphoton is developing 250W EUV source
- Target is 2015

Operational specification (Target)		HVM Source	
Performance	EUV Power	> 250W	
	CE	> 4.0 %	
	Pulse rate	100kHz	
	Availability	> 75%	
Technology	Droplet generator	Droplet size	< 20mm
	CO2 laser	Power	> 20kW
	Pre-pulse laser	Pulse duration	psec
	Debris mitigation	Magnet, Etching	> 15 days (>1500Mpls)



# High Power EUV Light Source

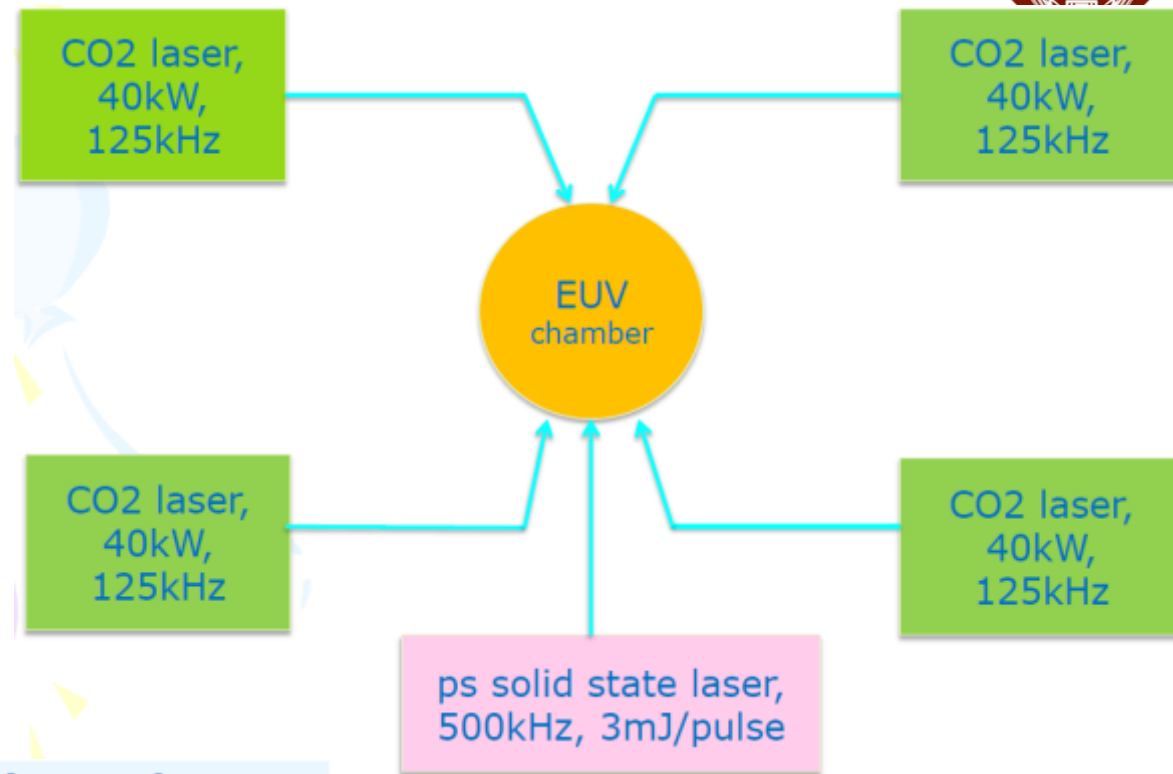
## Proto #2 System



# Scaling to shorter wavelength, multi kW operation



Scaling to 6.xnm,  
kW source



EUV IF power	1kW (6.xnm)
CO2 laser power	160kW
Conversion efficiency	1.5%/0/6%b.w. *
Collection efficiency	40%
Mirror reflectivity	70% **

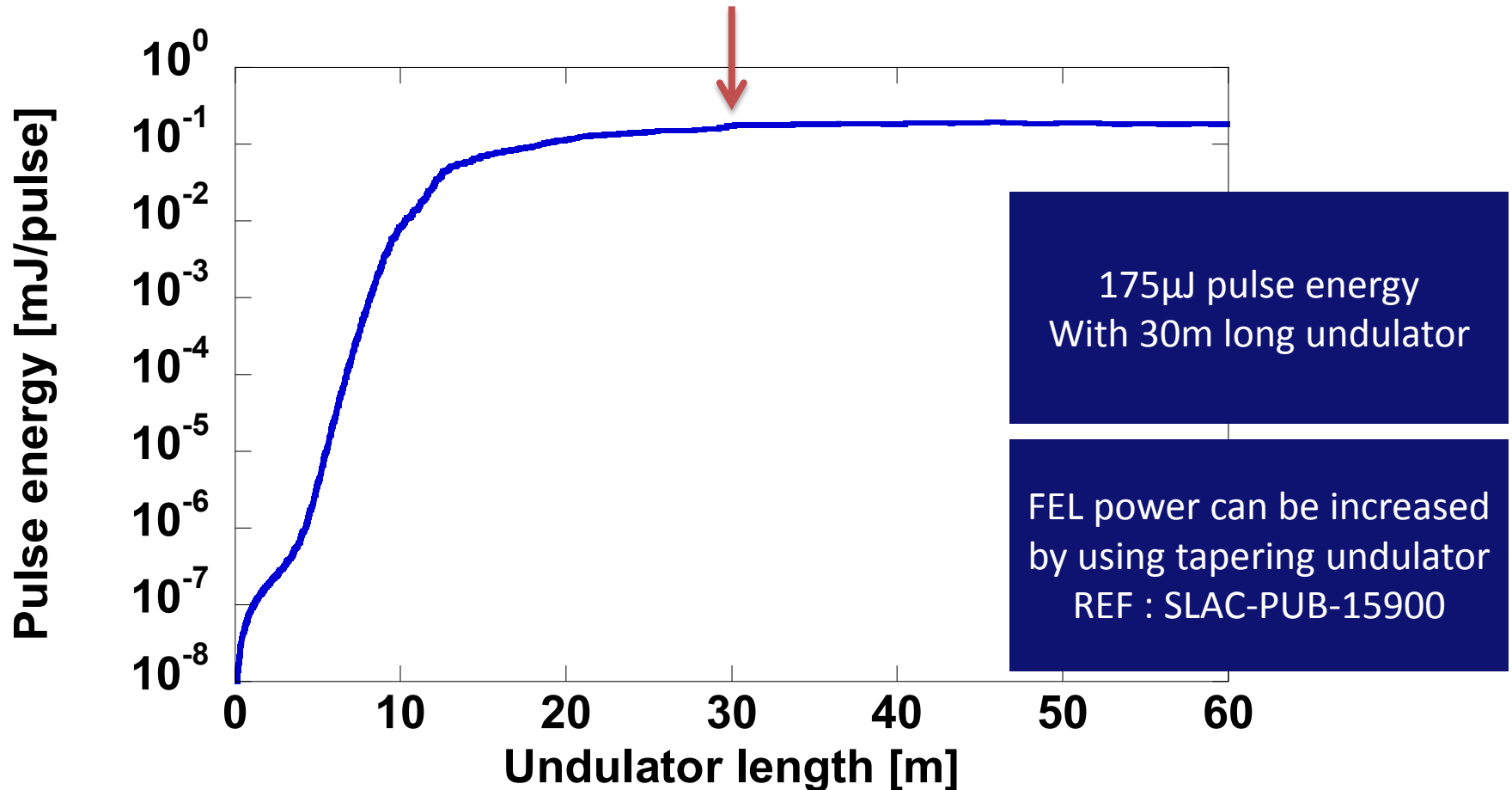
# GENESIS Calculation Parameters



Parameter	Value
Charge	300pC
Emittance	1 mmmrad
Energy Spread	1 E-4
Bunch length	200fs
Energy	331.13MeV
Undulation Period	9mm
K Value	1



# GENESIS Calculation

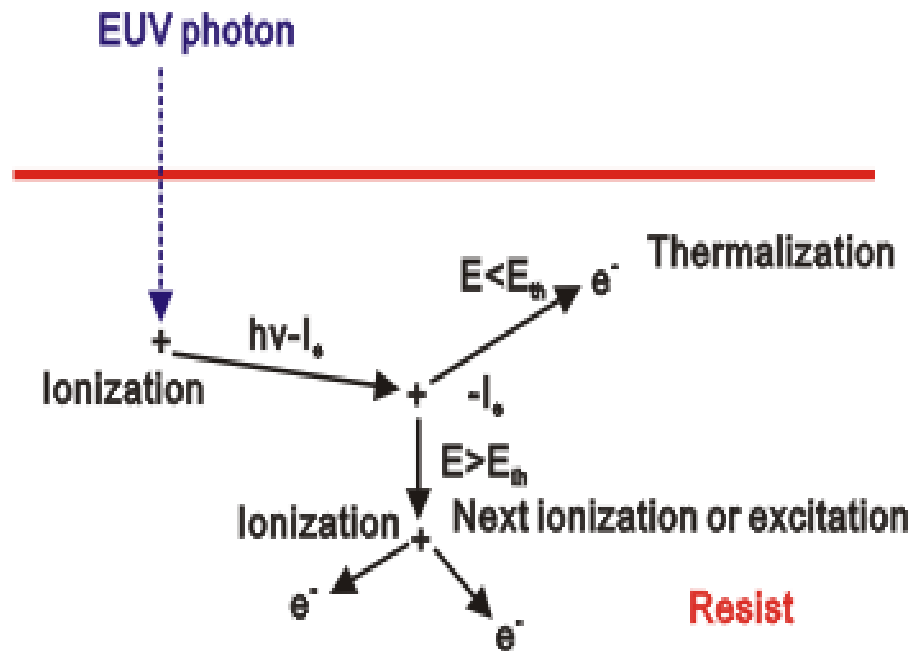




# Scaling of SASE-FEL power

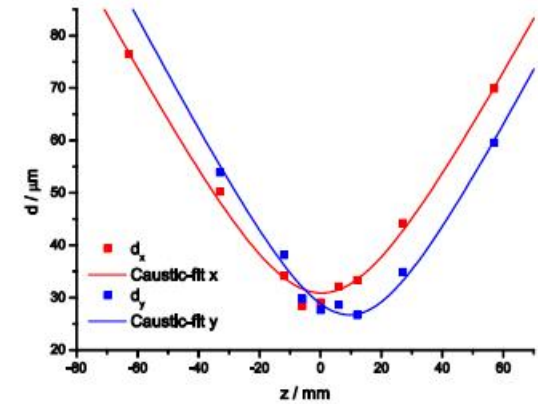
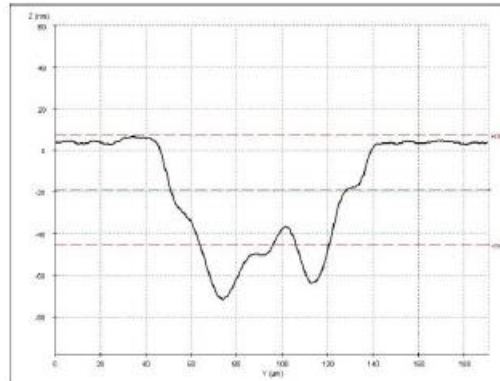
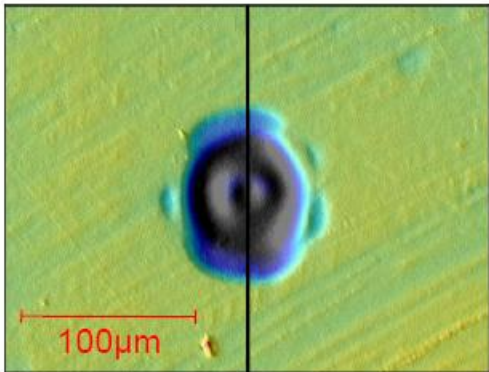
- MHz >100W
- 10MHz >1kW

# Chemically amplified resist



Resist sensitivity  $> 10\text{mJ}/\text{cm}^2$  (10ns, 13.5nm)

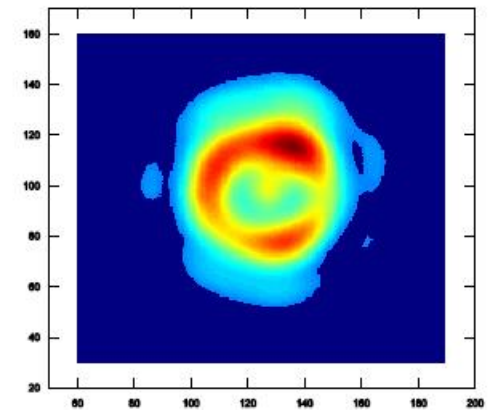
## Second moment beam diameter from PMMA



Ablative PMMA imprint, white-light interferometer

- ▶ Bulk PMMA sample at same position as phosphor
- ▶ Single pulses
- ▶ Assuming Lambert-Beer's law with
  - ▶ Ablation threshold  $7.2 \text{ mJ/cm}^2$
  - ▶ Attenuation length  $55.2 \text{ nm}$
- ▶ Second moment beam diameter

PMMA caustic



Beam profile

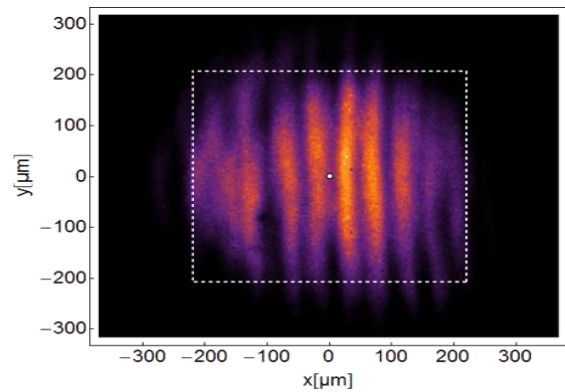
Issue 1 : ablation threshold < resist sensitivity

# Spatial coherence



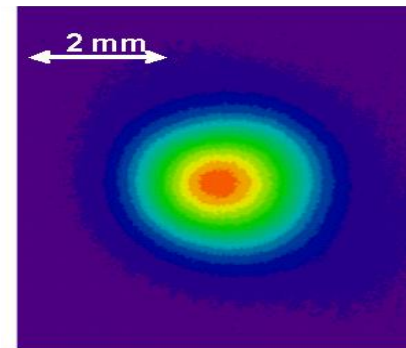
K of SASE FEL

$\sim 0.5$



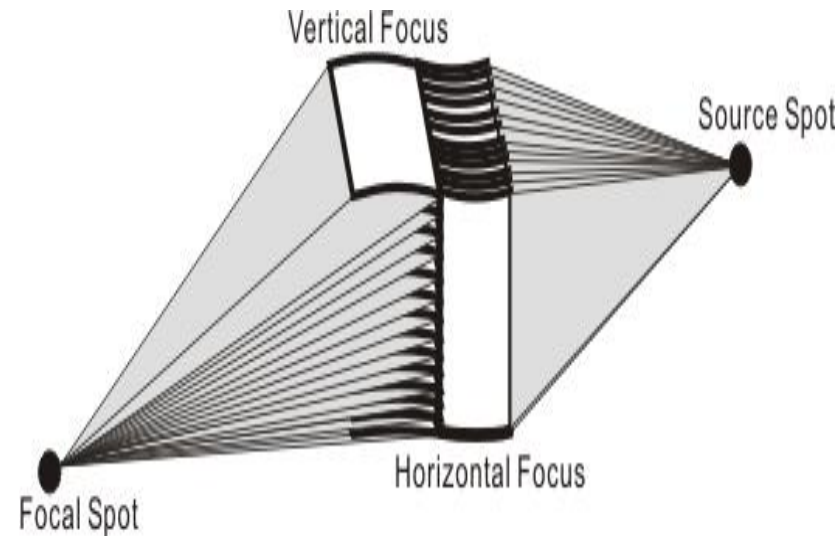
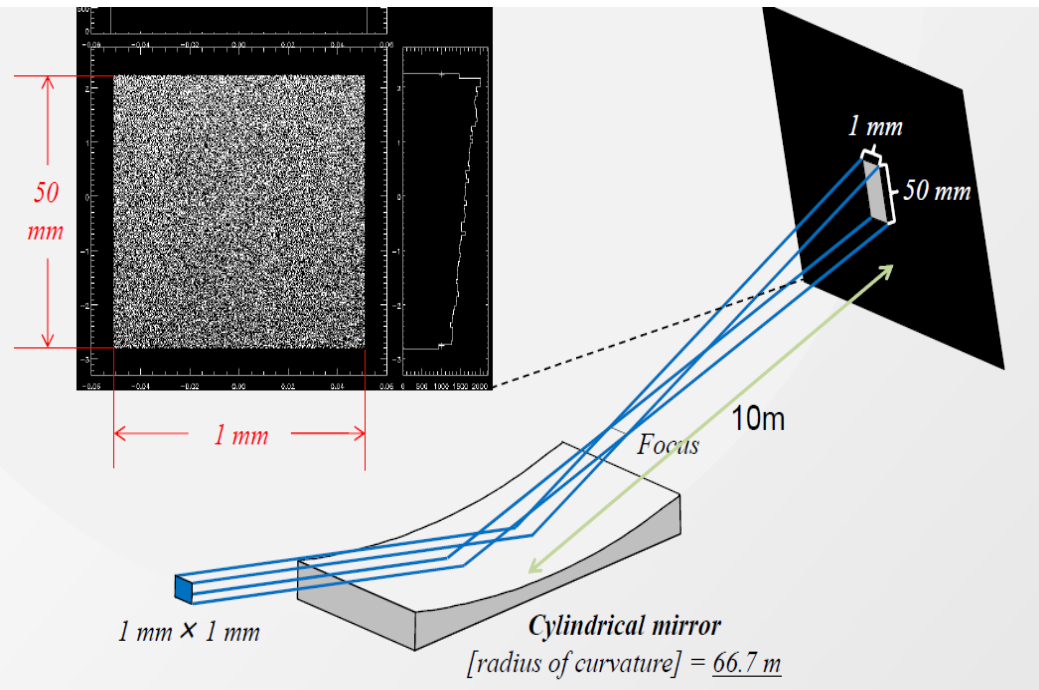
K of plasma source

$\sim 3.2 \times 10^{-9}$



Issue 2 : interference pattern

# Beam homogenizer by reflective optics

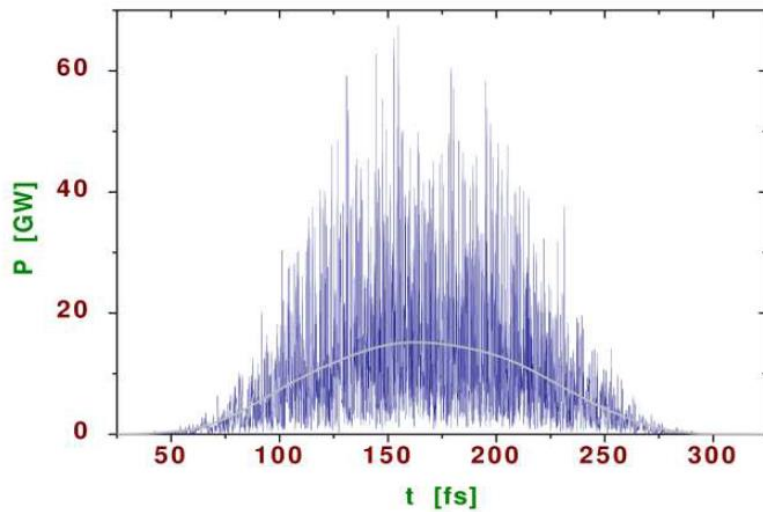


- Low roughness surface to avoid speckle pattern generation
- Higher transmission for low loss

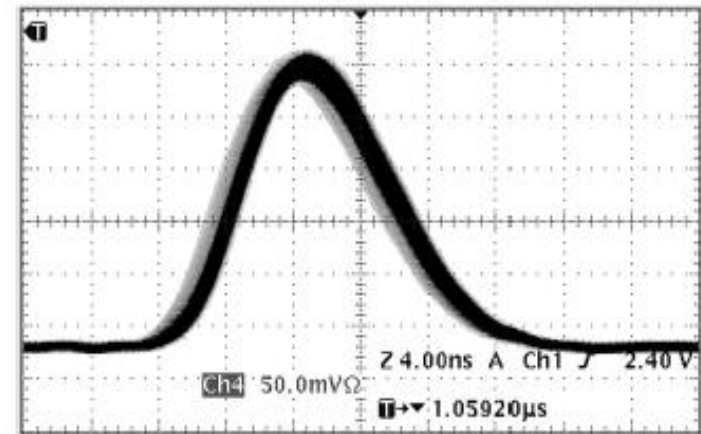
# Temporal pulse structure



## SASE FEL (FLASH)



## Sn laser plasma

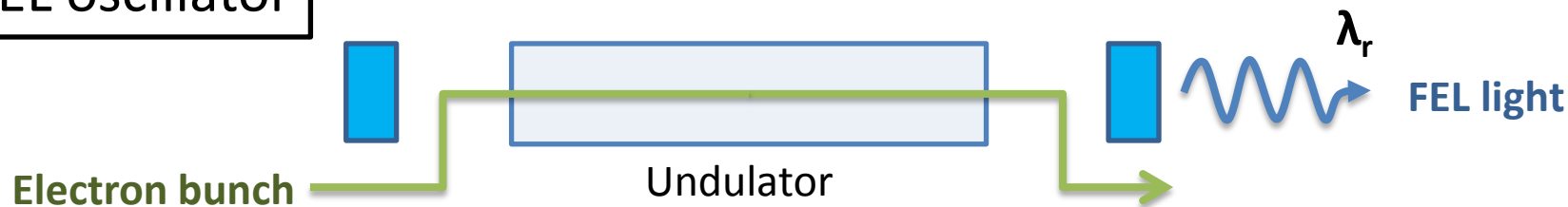


4ns/div

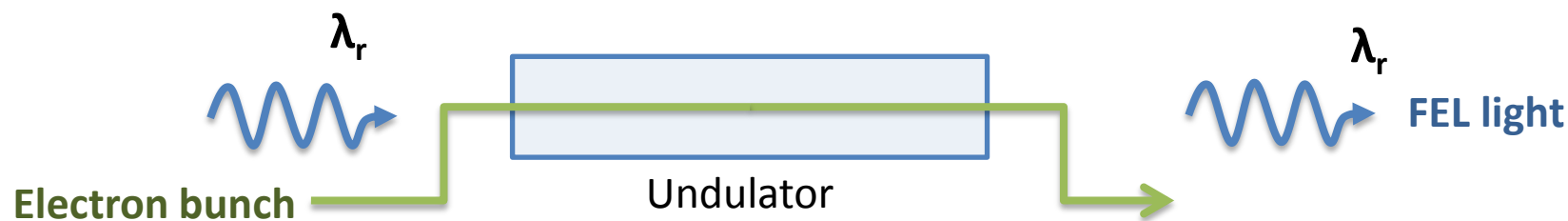
E.A. Schneidmiller and M.V. Yurkov, Coherence properties of the radiation FLASH, FLASH Seminar, September 17, 2013



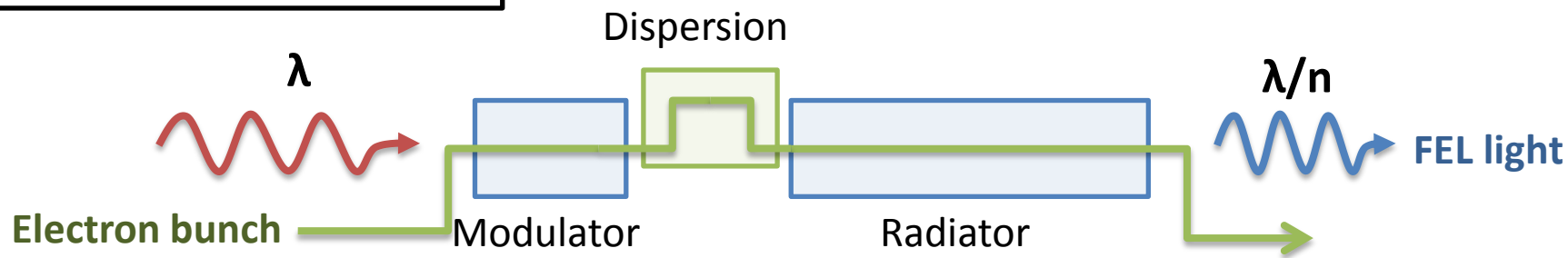
### FEL oscillator



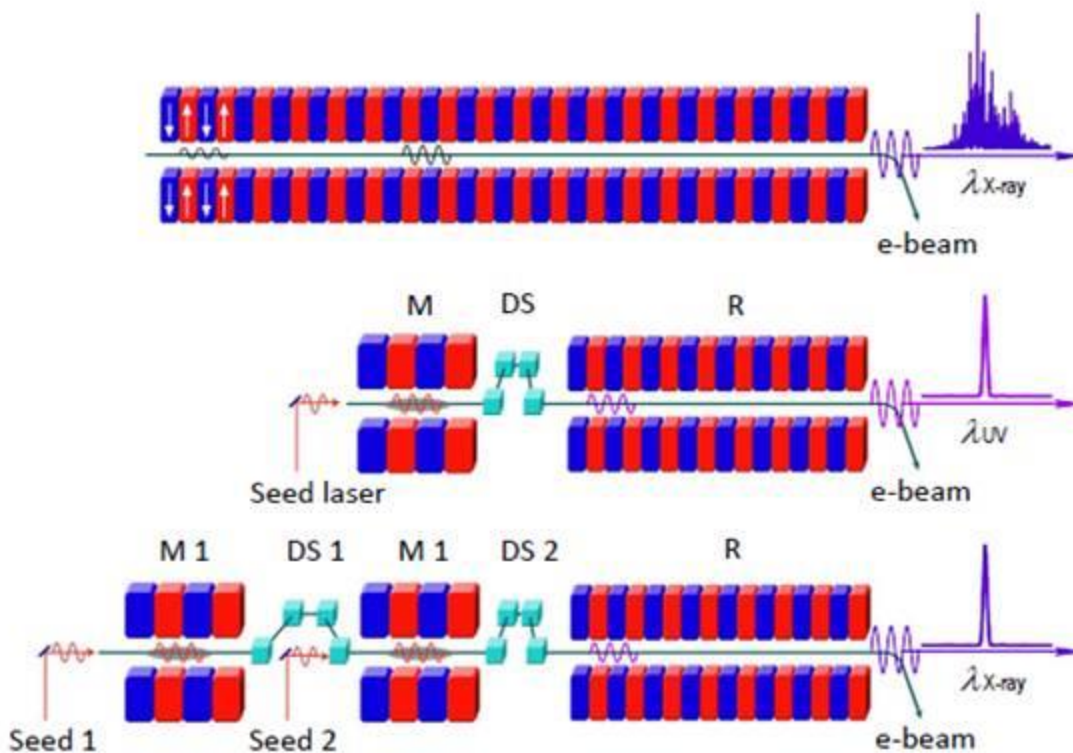
### Single-pass FEL (Seeded)



### Harmonic Generation







324nm, 100fs,  
20 $\mu$

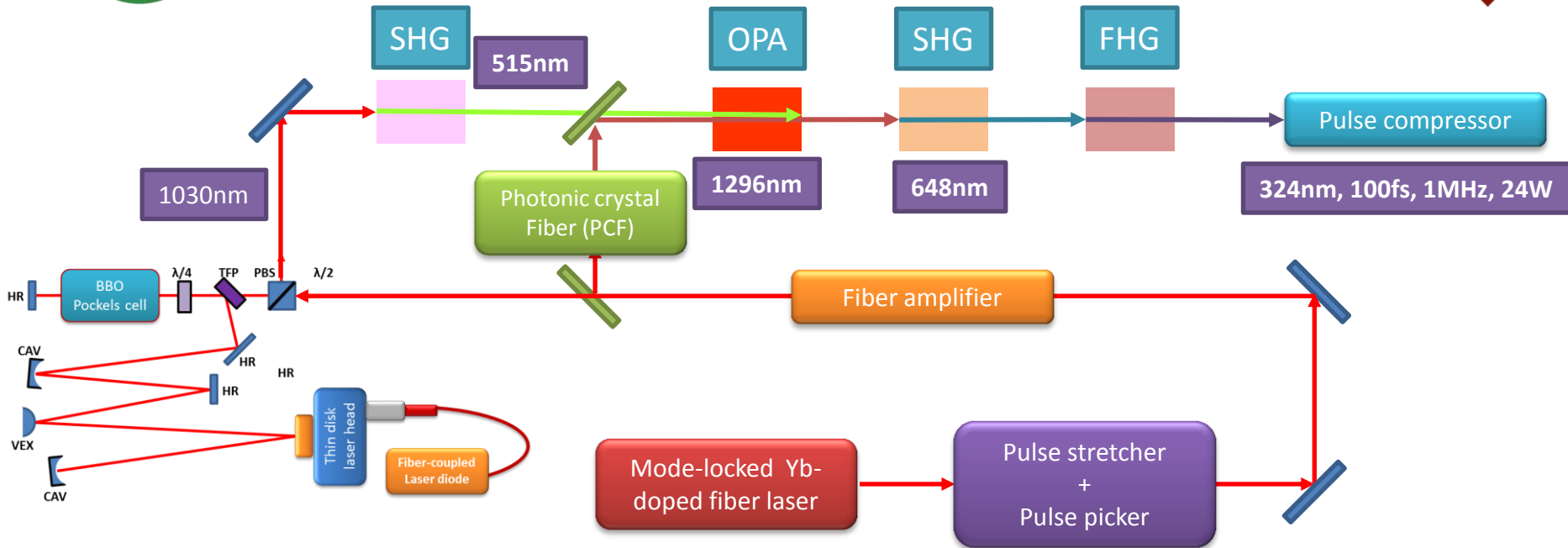
40.5nm

Fresh bunch injection HGHG

13.5nm



# EUV FEL Seed Source



Development of CW seeded picosecond mid-IR parametric light source pumped by the high average power Yb:YAG thin disc laser, Ondrej Nowak



# Conclusion



- Scaling of EUV source over kW
- SASE FEL can generate over kW power at 13.5nm
- Matching of FEL pulse for lithography
  1. Resist sensitivity & ablation
  2. Spatial coherence reduction
  3. Temporal smoothing